



TMMDB3 / TMMDB3TG

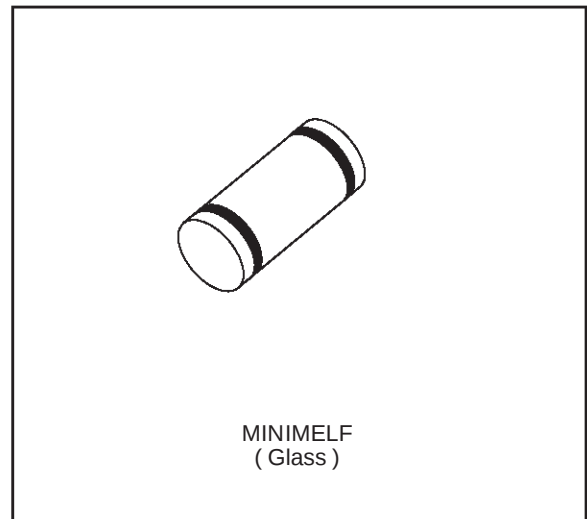
TRIGGER DIODES

FEATURES

- V_{BO} : 32V VERSION
- LOW BREAKOVER CURRENT

DESCRIPTION

High reliability glass passivation insuring parameter stability and protection against junction contamination.



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
P	Power dissipation on printed circuit (L = 10 mm)	Ta = 65 °C	150	mW
I _{TRM}	Repetitive peak on-state current	tp = 20 µs F = 100 Hz	2	A
Tstg Tj	Storage and operating junction temperature range		- 40 to + 125 - 40 to + 125	°C °C

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
R _{th} (j-a)	Junction to ambient	400	°C/W
R _{th} (j-l)	Junction to tie-point	300	°C/W

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ELECTRICAL CHARACTERISTICS (T_j = 25°C)

Symbol	Parameter	Test Conditions		Value		Unit
				TMMDB3	TMMDB3TG	
V _{BO}	Breakover voltage *	C = 22nF ** see diagram 1	MIN	28	30	V
			TYP	32	32	
			MAX	36	34	
[I+V _{BO} -I-V _{BO}]	Breakover voltage symmetry	C = 22nF ** see diagram 1	MAX	± 3	± 2	V
IΔV± I	Dynamic breakover voltage *	ΔI = [I _{BO} to I _F = 10 mA] see diagram 1	MIN	5		V
V _O	Output voltage *	see diagram 2	MIN	5		V
I _{BO}	Breakover current *	C = 22nF **	MAX	100	15	μA
t _r	Rise time *	see diagram 3	TYP	1.5		μs
I _B	Leakage current *	V _B = 0.5 V _{BO} max see diagram 1	MAX	10		μA

* Electrical characteristic applicable in both forward and reverse directions.

** Connected in parallel with the devices.

DIAGRAM 1 : Current-voltage characteristics

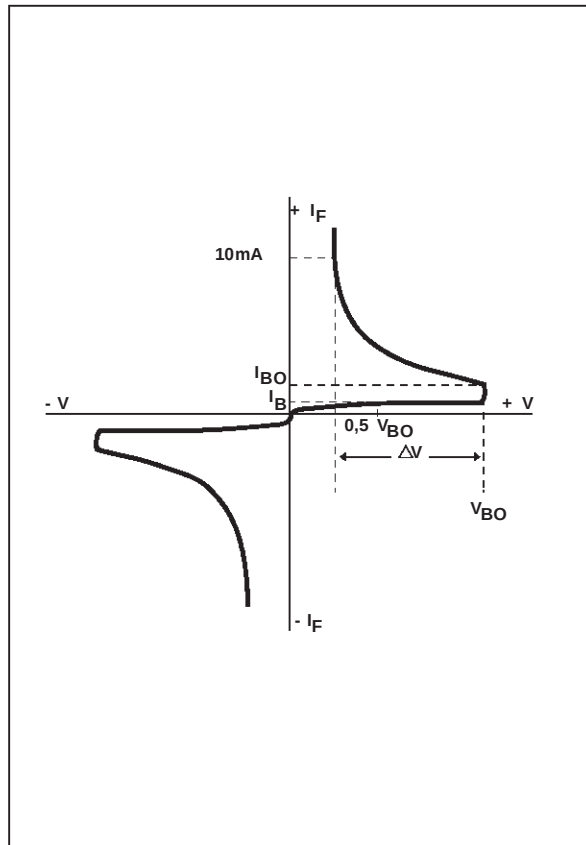


DIAGRAM 2 : Test circuit for output voltage

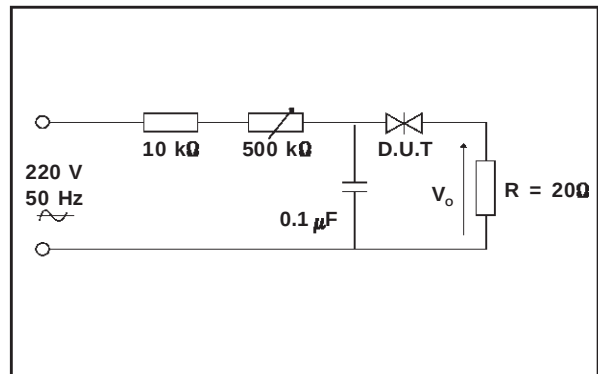


DIAGRAM 3 : Test circuit see diagram 2.
Adjust R for I_p = 0.5A

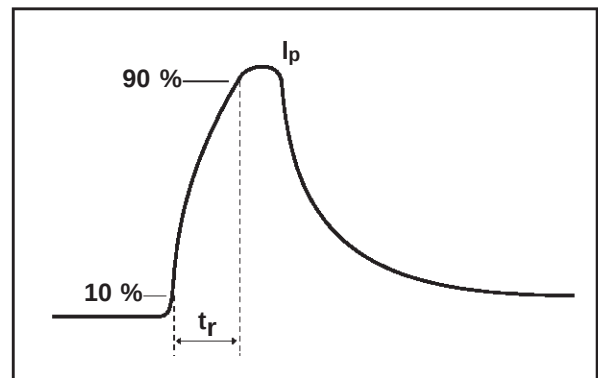


Fig.1 : Power dissipation versus ambient temperature (maximum values)

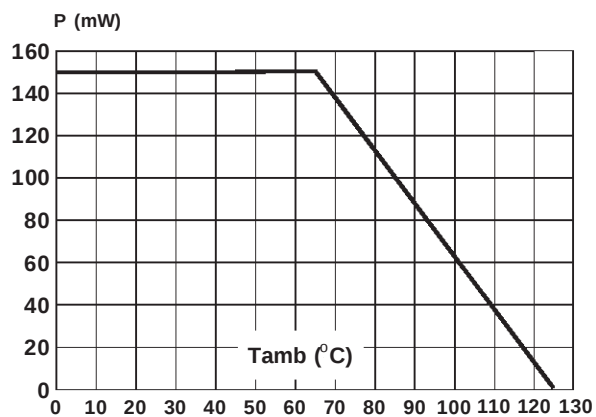


Fig.2 : Relative variation of V_{BO} versus junction temperature (typical values)

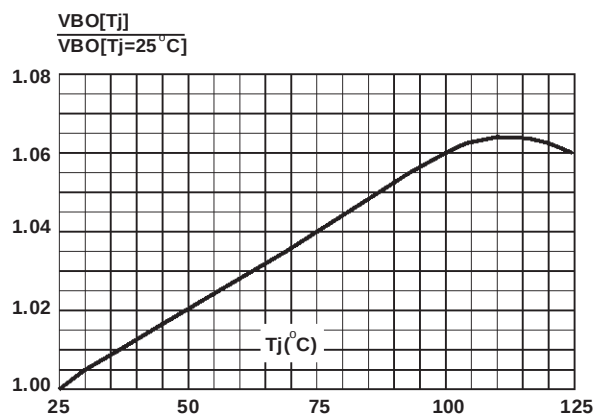
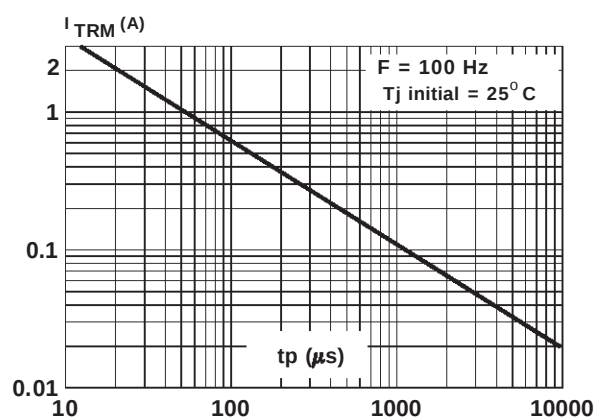
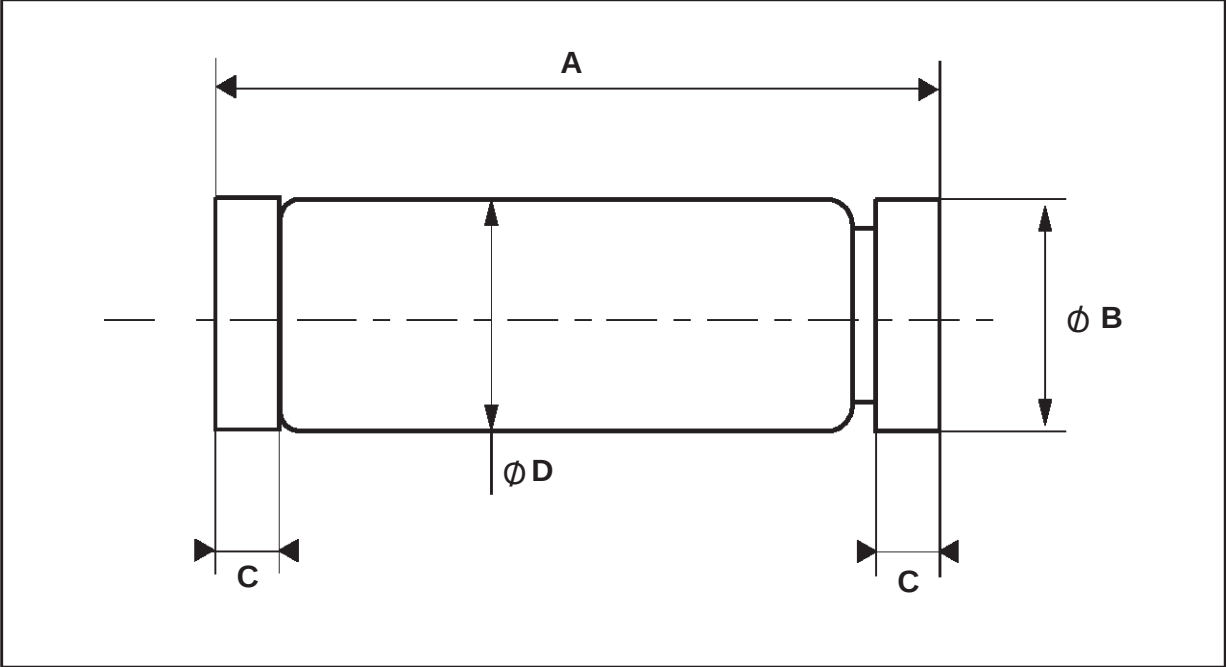


Fig.3 : Peak pulse current versus pulse duration (maximum values)



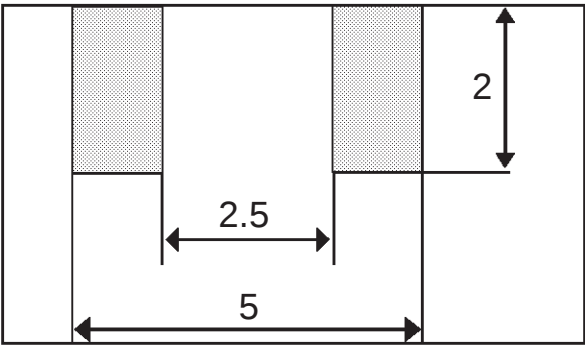
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PACKAGE MECHANICAL DATA (in millimeters)
MINIMELF Glass



REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	3.30	3.40	3.6	0.130	0.134	0.142
Ø B	1.59	1.60	1.62	0.063	0.063	0.064
C	0.40	0.45	0.50	0.016	0.018	0.020
Ø D		1.50			0.059	

FOOT PRINT (in millimeters)



- **Marking** : Clear
- Cooling method by convection and conduction
- Polarity : N A
- Stud torque : N A
- Weight : 0.0380 g

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